

CUTTING MACHINE

ABSTRACT OF THE DISCLOSURE

There is provided a cutting machine for cutting a wafer using a cutting blade. The cutting machine includes a shape storage section, a shape measurement unit, a determination section, and an end face correction device. The shape storage section stores a cross-sectional shape of a support surface, which a mount of a cutting unit has, in an axial direction of a spindle. The shape measurement unit contactlessly measures the cross-sectional shape of the support surface in the axial direction of the spindle. Through a comparison between the cross-sectional shape stored in the shape storage section and the cross-sectional shape measured by the shape measurement unit, the determination section determines whether or not the support surface needs a correction. The end face correction device corrects a shape of the support surface.

[Fig. 1]